



Product Specification

Product:	Encapsulation Paste
Part Number:	09L-4406

Application Scope :

This paste is suitable for external marking and surface encapsulation of circuits and resistor plates. It can be used on substrates including glass, ceramics, stainless steel, and aluminum alloys.

Usage Conditions :

Substrate	Thick-film circuits, glass, ceramics, metals, etc.
Usage Method	Printing, 200-250 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Solidify	Furnace drying at 150–200°C for 20–30 minutes (the curing temperature can be within the range of 150–200°C, and the curing time may be adjusted according to actual conditions)
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	$\leq 8\mu\text{m}$	FOG test
2	Viscosity	80~150Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, $25\pm 1^\circ\text{C}$
3	Appearance	White, Black, Blue, Green	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1)



Characteristics		Standard	Test Method And Conditions
4	Acid Resistance	Fine	5% sulfuric acid, no change after 30 minutes
5	Insulation Coefficient	----	RCJ-30
6	Breakdown Voltage	----	CS262673A

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.